

8K X 8 BIT HIGH SPEED CMOS SRAM

Rev. 1.2

REVISION HISTORY

<u>Revision</u>	<u>Description</u>	<u>Issue Date</u>
Rev. 1.0	Initial Issue	Aug.27.2010
Rev. 1.1	Delete E-grade , revise Ordering Information in page 10	Apr. 06. 2012
Rev. 1.2	Removed Package Type : SOJ	Apr. 08. 2019

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FEATURES

Fast access time : 20ns
 Low power consumption:
 Operating current : 30mA (TYP.)
 Standby current : 2μA (TYP.)

■ Single 5V power supply

■ All inputs and outputs TTL compatible

Fully static operationTri-state output

■ Data retention voltage : 2.0V (MIN.)

■ Green package available

■ Package: 28-pin 8mm x 13.4mm sTSOP

GENERAL DESCRIPTION

The LY6564 is a 65,536-bit high speed CMOS static random access memory organized as 8,192 words by 8 bits. It is fabricated using very high performance, high reliability CMOS technology. Its standby current is stable within the range of operating temperature.

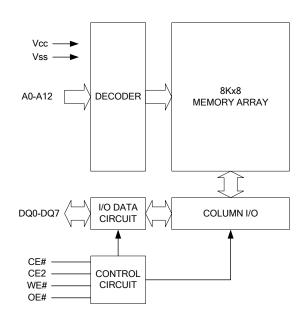
The LY6564 is well designed for high speed system applications, and particularly well suited for battery back-up nonvolatile memory application.

The LY6564 operates from a single power supply of 5V and all inputs and outputs are fully TTL compatible

PRODUCT FAMILY

Product	Operating	Vcc Range	Speed	Power D	issipation	
Family	Temperature	vcc Range	Speed	Standby(IsB1,TYP.)	Operating(Icc,TYP.)	
LY6564(LL)	0 ~ 70℃	4.5 ~ 5.5V	20ns	2µA	30mA	
LY6564(LLI)	-40 ~ 85°C	4.5 ~ 5.5V	20ns	2µA	30mA	

FUNCTIONAL BLOCK DIAGRAM



PIN DESCRIPTION

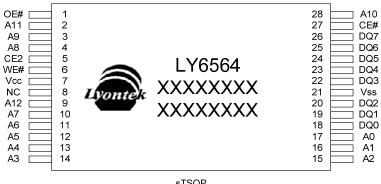
SYMBOL	DESCRIPTION
A0 - A12	Address Inputs
DQ0 – DQ7	Data Inputs/Outputs
CE#, CE2	Chip Enable Inputs
WE#	Write Enable Input
OE#	Output Enable Input
Vcc	Power Supply
Vss	Ground
NC	No Connection

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PIN CONFIGURATION



sTSOP

ABSOLUTE MAXIMUN RATINGS*

PARAMETER	SYMBOL	RATING	UNIT
Voltage on Vcc relative to Vss	V _{T1}	-0.5 to 6.5	V
Voltage on any other pin relative to Vss	V _{T2}	-0.5 to Vcc+0.5	V
Operating Temperature	т.	0 to 70(C grade)	${\mathbb C}$
Operating Temperature	TA	-40 to 85(I grade)	C
Storage Temperature	Тѕтс	-65 to 150	$^{\circ}\!\mathbb{C}$
Power Dissipation	Po	1	W
DC Output Current	Іоит	50	mA

^{*}Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to the absolute maximum rating conditions for extended period may affect device reliability.

TRUTH TABLE

MODE	CE#	CE2	OE#	WE#	I/O OPERATION	SUPPLY CURRENT
Standby	Н	Х	Х	Х	High-Z	Is _B 1
Stariuby	Х	L	Х	Х	High-Z	ISB1
Output Disable	L	Н	Н	Н	High-Z	Icc
Read	L	Н	L	Н	D оит	Icc
Write	L	Η	Х	L	Din	Icc

Note: $H = V_{IH}, L = V_{IL}, X = Don't care.$

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DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP. *4	MAX.	UNIT
Supply Voltage	Vcc		4.5	5.0	5.5	V
Input High Voltage	V _{IH} *1		2.4	-	Vcc+0.5	V
Input Low Voltage	V _{IL} *2		- 0.5	-	0.8	V
Input Leakage Current	lu	$V_{CC} \ge V_{IN} \ge V_{SS}$	- 1	-	1	μA
Output Leakage Current	llo	Vcc ≧ Vouт ≧ Vss, Output Disabled	- 1	-	1	μA
Output High Voltage	Vон	Iон = -1mA	2.4	-	-	V
Output Low Voltage	Vol	I _{OL} = 2mA	-	-	0.4	V
Average Operating Power supply Current	Icc	Cycle time = Min. CE# = V _{IL} and CE2 = V _{IH} , I _{I/O} = 0mA Other pins at V _{IH} or V _{IL}	-	30	55	mA
Standby Power	Isa	CE# = Viн or CE2 = Vil Others at Vil or Vih	-	1	5	mA
Supply Current	I _{SB1}	CE# \ge Vcc-0.2V or CE2 \le 0.2V Other pins at 0.2V or Vcc-0.2V	-	2	50	μA

- 1. $V_{IH}(max) = V_{CC} + 3.0V$ for pulse width less than 10ns.
- 2. VIL(min) = Vss 3.0V for pulse width less than 10ns.
- 3. Over/Undershoot specifications are characterized, not 100% tested.
- 4. Typical values are included for reference only and are not guaranteed or tested. Typical valued are measured at Vcc = Vcc(TYP.) and TA = 25° C

CAPACITANCE (TA = 25° C, f = 1.0MHz)

PARAMETER	SYMBOL	MIN.	MAX	UNIT
Input Capacitance	Cin	-	6	pF
Input/Output Capacitance	Ci/o	-	8	pF

Note: These parameters are guaranteed by device characterization, but not production tested.

AC TEST CONDITIONS

Input Pulse Levels	0.2V to Vcc - 0.2V
Input Rise and Fall Times	3ns
Input and Output Timing Reference Levels	1.5V
Output Load	$C_L = 30pF + 1TTL$, $I_{OH}/I_{OL} = -4mA/8mA$





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AC ELECTRICAL CHARACTERISTICS

(1) READ CYCLE

PARAMETER	SYM.	LY65	UNIT	
		MIN.	MAX.	-
Read Cycle Time	trc	20	-	ns
Address Access Time	taa	-	20	ns
Chip Enable Access Time	tace	-	20	ns
Output Enable Access Time	toe	-	8	ns
Chip Enable to Output in Low-Z	tcLz*	4	-	ns
Output Enable to Output in Low-Z	tolz*	0	-	ns
Chip Disable to Output in High-Z	tcHZ*	-	8	ns
Output Disable to Output in High-Z	tonz*	-	8	ns
Output Hold from Address Change	tон	3	-	ns

(2) WRITE CYCLE

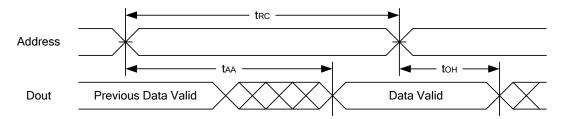
PARAMETER	SYM.	LY65	LY6564-20		
		MIN.	MAX.		
Write Cycle Time	twc	20	-	ns	
Address Valid to End of Write	taw	16	-	ns	
Chip Enable to End of Write	tcw	16	-	ns	
Address Set-up Time	tas	0	-	ns	
Write Pulse Width	twp	11	-	ns	
Write Recovery Time	twr	0	-	ns	
Data to Write Time Overlap	tow	9	-	ns	
Data Hold from End of Write Time	tон	0	-	ns	
Output Active from End of Write	tow*	5	-	ns	
Write to Output in High-Z	twnz*	-	9	ns	

^{*}These parameters are guaranteed by device characterization, but not production tested.



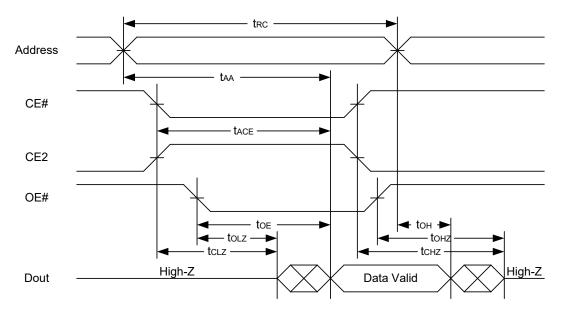
TIMING WAVEFORMS

READ CYCLE 1 (Address Controlled) (1,2)



READ CYCLE 2 (CE# and CE2 and OE# Controlled) (1,3,4,5)

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Notes:

- 1.WE# is high for read cycle.
- 2.Device is continuously selected OE# = low, CE# = low, CE2 = high.

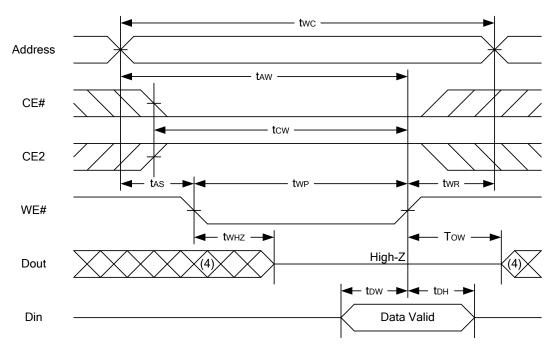
 3.Address must be valid prior to or coincident with CE# = low, CE2 = high; otherwise t_{AA} is the limiting parameter.
- 4.tcLz, toLz, tcHz and toHz are specified with CL = 5pF. Transition is measured ±500mV from steady state.
- 5.At any given temperature and voltage condition, tcHz is less than tcLz, toHz is less than toLz.



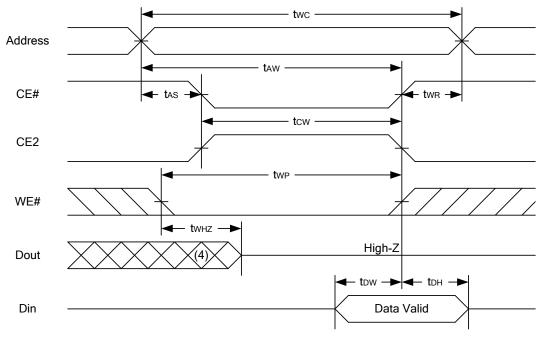
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WRITE CYCLE 1 (WE# Controlled) (1,2,3,5,6)



WRITE CYCLE 2 (CE# and CE2 Controlled) (1,2,5,6)



Notes:

- 1.WE#, CE# must be high or CE2 must be low during all address transitions.
- 2.A write occurs during the overlap of a low CE#, high CE2, low WE#.
- 3.During a WE#controlled write cycle with OE# low, twp must be greater than twHz + tpw to allow the drivers to turn off and data to be placed on the bus.
- 4. During this period, I/O pins are in the output state, and input signals must not be applied.
- 5.If the CE#low transition and CE2 high transition occurs simultaneously with or after WE# low transition, the outputs remain in a high impedance state.
- 6.tow and tw_{HZ} are specified with C_{L} = 5pF. Transition is measured $\pm 500 \text{mV}$ from steady state.

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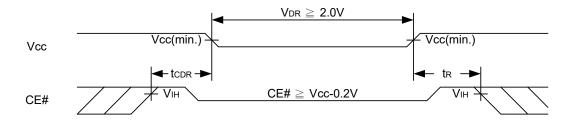
DATA RETENTION CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Vcc for Data Retention		CE# \geq V _{CC} - 0.2V or CE2 \leq 0.2V	2.0	-	5.5	V
Data Retention Current	I _{DR}	V_{CC} = 2.0V CE# \geq V_{CC} - 0.2V or CE2 \leq 0.2V Others at 0.2V or V_{CC} -0.2V	-	0.5	30	μΑ
Chip Disable to Data Retention Time	ICDD	See Data Retention Waveforms (below)	0	-	-	ns
Recovery Time	t _R		t _{RC*}	-	-	ns

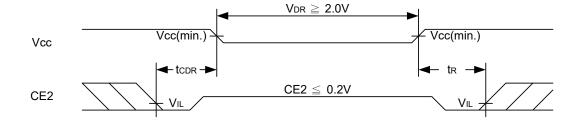
tRC* = Read Cycle Time

DATA RETENTION WAVEFORM

Low Vcc Data Retention Waveform (1) (CE# controlled)



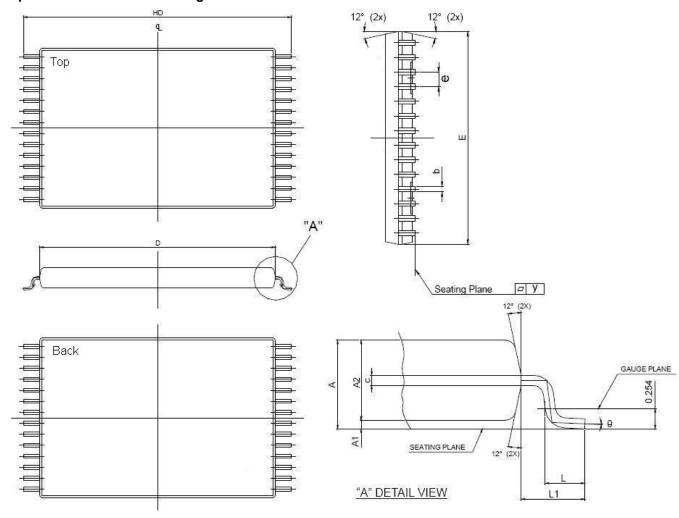
Low Vcc Data Retention Waveform (2) (CE2 controlled)



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PACKAGE OUTLINE DIMENSION

28 pin 8x13.4mm sTSOP Package Outline Dimension



SYMBOLS	DIMENSIO	ONS IN MILL	IMETERS	DIMENSIONS IN INCHES		
OTWIDOLO	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.00	1.10	1.20	0.040	0.043	0.047
A1	0.05	-	0.15	0.002	-	0.006
A2	0.91	1.00	1.05	0.036	0.039	0.041
b	0.17	0.22	0.27	0.007	0.009	0.011
С	0.07	0.15	0.23	0.003	0.006	0.009
HD	13.20	13.40	13.60	0.520	0.528	0.535
D	11.60	11.80	12.00	0.457	0.465	0.472
E	7.80	8.00	8.20	0.307	0.315	0.323
е	-	0.55	-	-	0.0216	-
L	0.30	0.50	0.70	0.012	0.020	0.028
L1	0.675	-	-	0.027	-	-
Y	0.00	-	0.076	0.000	-	0.003
θ	0°	3°	5°	0°	3°	5°



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ORDERING INFORMATION

Package Type	Access Time	Power Type	Temperature	Packing	Lyontek Item No.
	(Speed)(ns)		Range(°ℂ)	Туре	
32Pin	20	Ultra Low Power	0°C~70°C	Tray	LY6564RL-20LL
(8mmx13.4mm) sTSOP				Tape Reel	LY6564RL-20LLT
\$130F			-40°C ~85°C	Tray	LY6564RL-20LLI
				Tape Reel	LY6564RL-20LLIT



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